

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant	:	Yuji Okawa
Appl. No.	:	10/809,566
Filed	:	March 25, 2004
For	:	WAFER BACK SURFACE TREATING METHOD AND DICING SHEET ADHERING APPARATUS
Examiner	:	Thanhha S Pham
Group Art Unit	:	2813

**SUPPLEMENTAL SUBMISSION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Further in response to the Office Action dated September 19, 2006, and in response to the Advisory Action dated December 6, 2006, Applicants submit the following amendments and remarks:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.